FY2019 Q2 Financial Results Briefing



(Securities Identification Code: 6787)

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FY2019 2Q Results

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Technology Roadmap



FY2019 Q2 settlement highlights

Net sales

Net sales decreased 2,700 million yen to 5,910 million yen.

- Automotive increased 2.6% year on year to 27,400 million yen
- •Smartphone decreased 23.8% year on year to 14,700 million yen
- Sales in other fields increased 7.6% year on year to 17,000 million yen

Profit

Operating income amounted to 3,400 million yen, down 2,300 million yen over previous year.

Ordinary income totaled to 3,000 million yen, down 3,300 million yen over previous year.

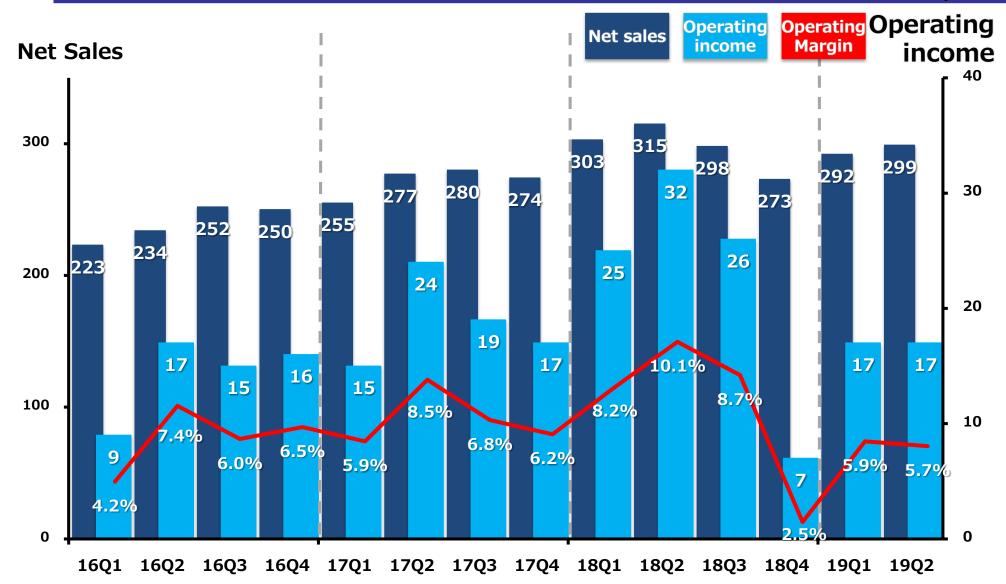
Net income to owners of parent company amounted to 2,400 million yen, down 2,900 million yen over previous year.

FY2019 Q2 Consolidated Business Performance (100 million yen)

	FY2018Q2 FY2019Q2 performance	FY2019Q2	Year-on-year	
		performance	Increase	%
Net sales	618	591	-27	-4.3%
Operating income	57	34	-23	-39.9%
	9.2%	5.8%		
Ordinary income	63	30	-33	-52.4%
	10.2%	5.1%		
Net income	53	24	-29	-55.6%
	8.6%	4.0%		
Average Exchange rate (Yen/USD)	110.64	108.66		

Net sales, Operating income

(100 million yen)





FY2019 Q2 Product Revenue

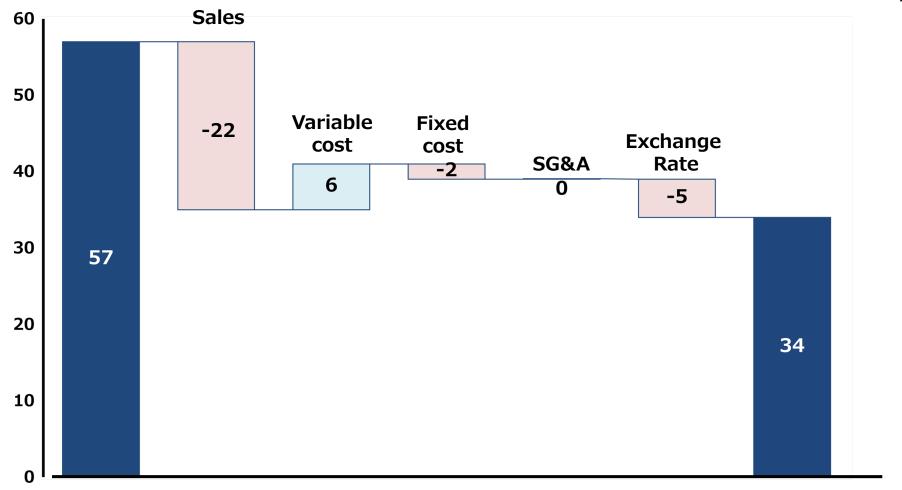
(100 million yen)

	FY2018		8 Q2 FY201		Difference	
	Sales	Operating income	Sales	Operating i n c o m e	Sales	Operating i n c o m e
		%		%	%	%
Automotive	267	19	274	15	7	-4
		7.1%		5.5%	2.6%	-21.1%
Smartphone 193	193	29	147	14	-46	-15
		14.5%		9.5%	-23.8%	-51.7%
Others 158	9	170	5	12	-4	
		5.9%		2.9%	7.6%	-44.4%
Total	618	57	591	34	-27	-23
		9.2%		5.8%	-4.3%	-39.9%



Analysis of operating income change FY2018 Q2→FY2019 Q2

(100 million yen)



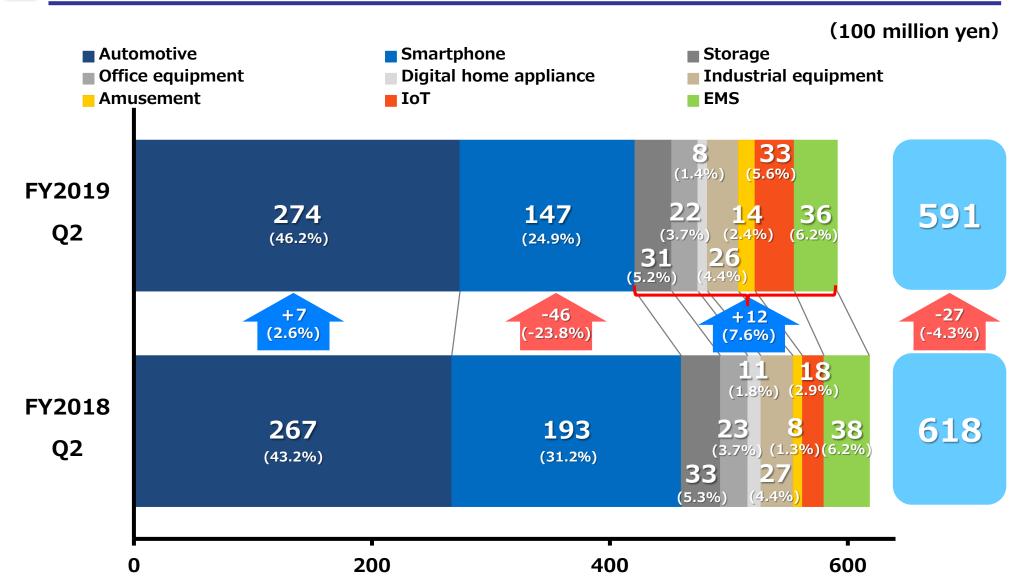
FY2018Q2 performance

Exchange Rate 110.64Yen/us\$

FY2019Q2 performance Exchange Rate 108.66Yen/us\$



FY2019 Q2 Sales Performance by Product Application

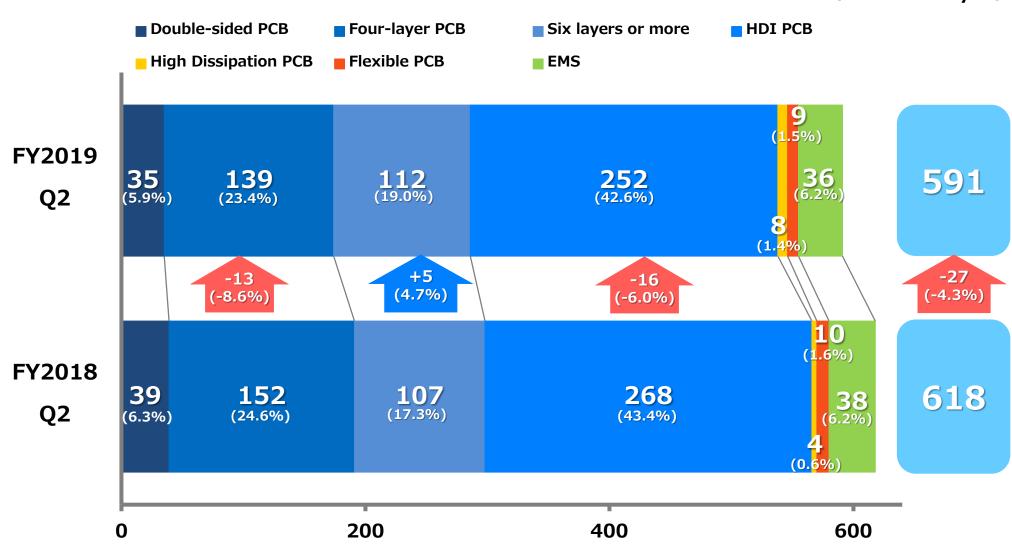






FY2019 Q2 Sales Performance by Product Specification

(100 million yen)



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Outlook for the current term

Ocerview

- · Automotive will remain at the same level as the first half
- · Smartphone will remain at the same level as the first half
- Sales in other fields, IoT and EMS will grow

Investment

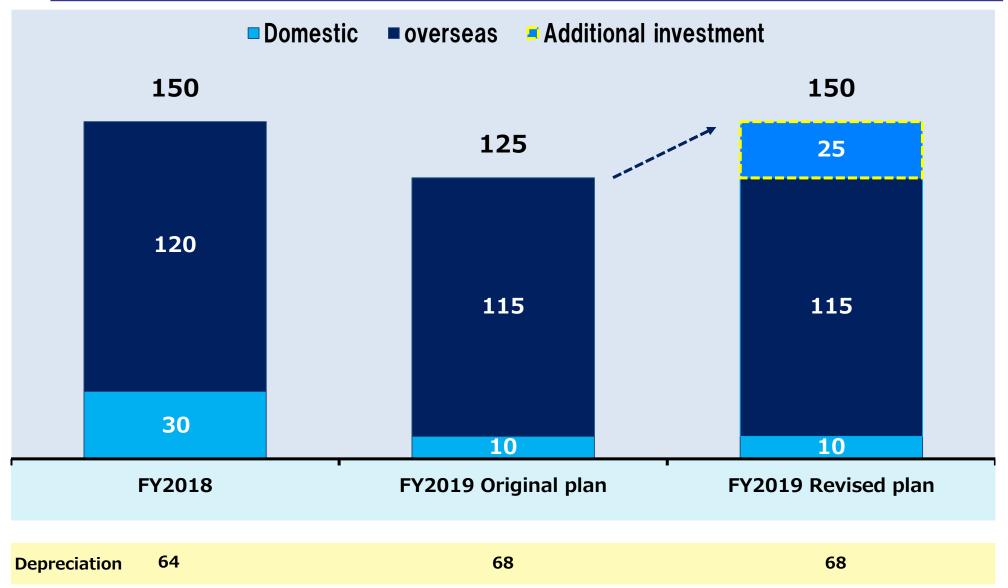
- Vietnam Plant#1 factory: we will invest in EMS and flexible
- Vietnam Plant#2 factory: we will invest in an automotive factory
- Vietnam Plant#3 and Tang Long factory:
 we will make 5G upfront investment



FY2019 Full-year forecast

	FY2019 plan	FY2019 Q2 results	FY2019 full-year forecast
Net Sales	1,200	591	609
Operating Income	75	34	41
	6.3%	5.8%	6.7%
Ordinary Income	63	30	33
	5.3%	5.1%	5.4%
Net income	53	24	29
	4.4%	4.0%	4.7%
Exchange rate (J P Y / U S D)	111.00	108.66	108.00

Investment plan



Vietnam factory strategy



Smartphone

5G Smartphone

Automotive developed products



High frequency module

Meiko-Towada Vietnam

EMS

Vietnam Plant #3

MSAP · Automotive developed products



Tang Long Plant

High frequency module

5Gmodule

Smartphone



Vietnam Plant #3

Automotive

MLB

HDI



Vietnam Plant #1

Flexible PCB/EMS

Flexible PCB

Longcheer Joint Venture

IoT / AI Appliance



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FY2019 2Q Results

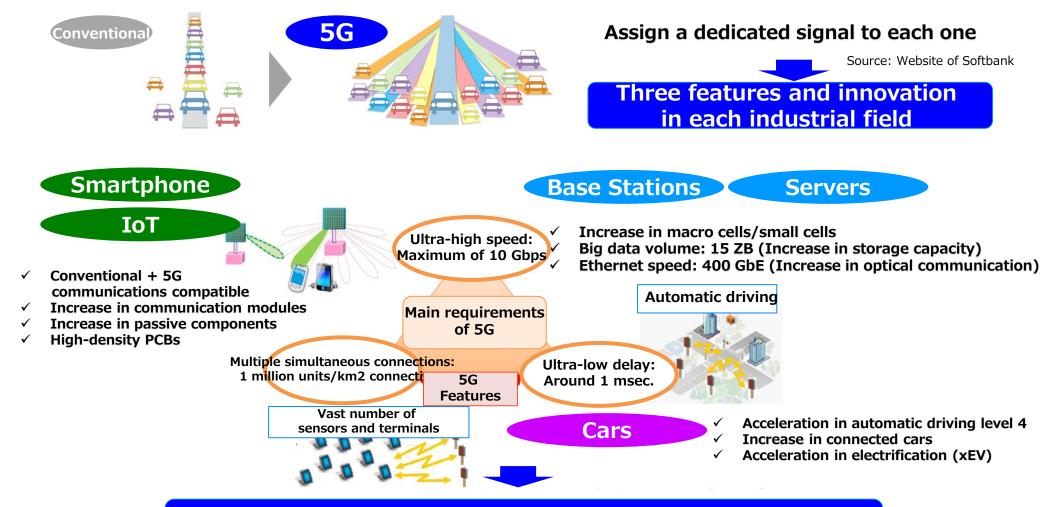
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Transformation brought about by 5G

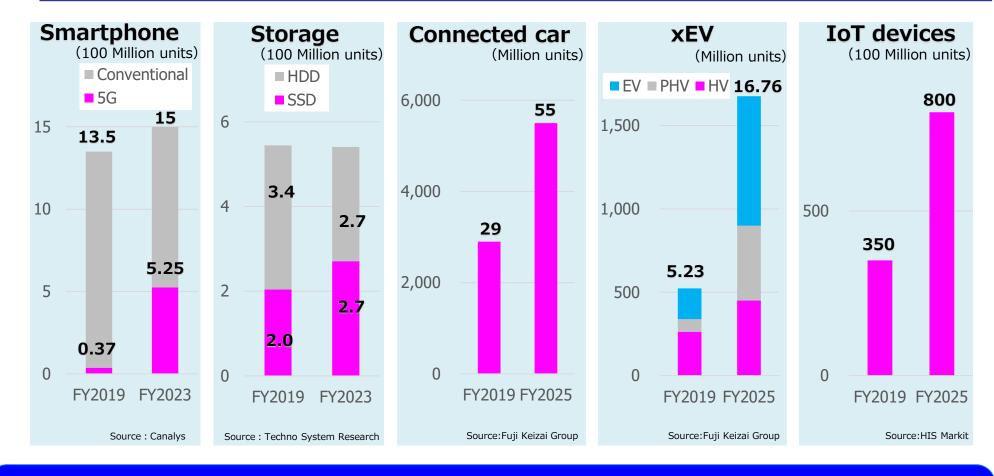


New markets for printed wiring boards (PCB) will be created in 5G and the existing market will expand

Source: Ministry of Internal Affairs and Communications



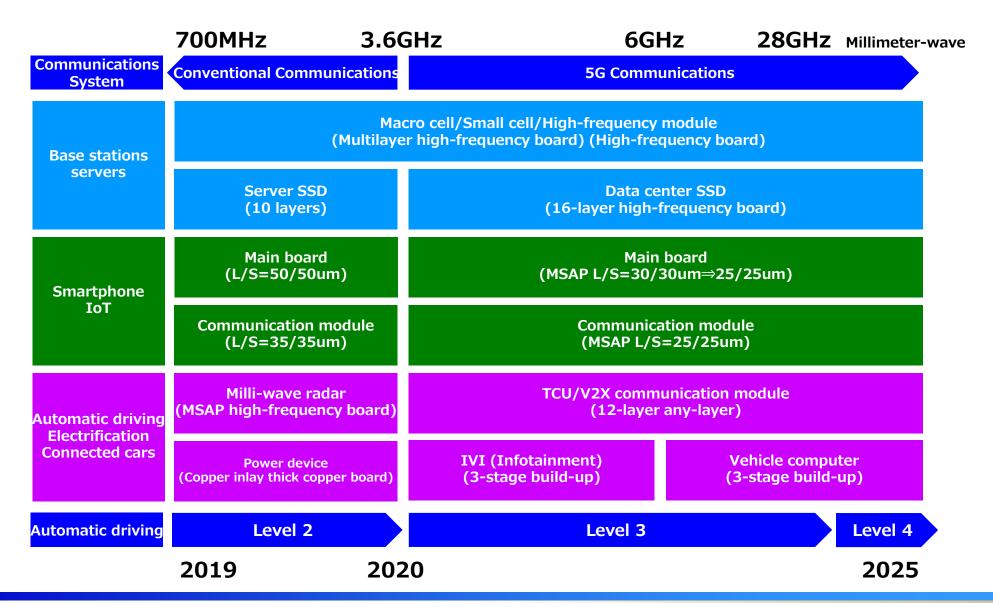
5G market trends (sales volume)



- ■5G smartphones have become popular, SSDs have increased due to the increase in big data volume
- The number of connected cars supporting 5G increases, xEV significantly increases
- IoT equipment continues to grow steadily
- Demand for higher-density build-up boards and boards for vehicles will increase



Technology development roadmap for 5G





5G development example

Unit

TCU / V2X communication module for connected cars

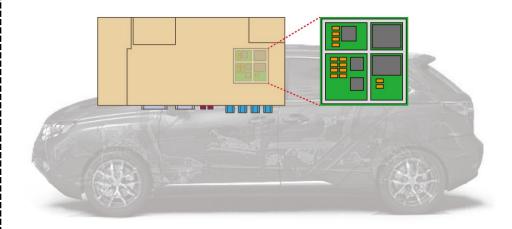
application

Using a mobile communication system, two-way communication between the car and cloud servers, infrastructure, and other cars

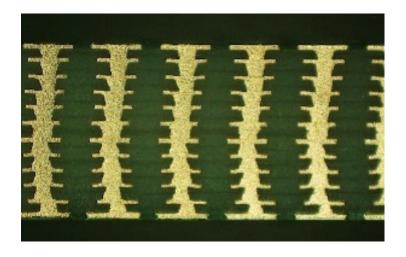
feature

High-density printed wiring board on which 5G communication chip is mounted

Communication module



High-density PCB



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These forward-looking statements are not historical facts, rather they represent assumptions and beliefs based on comprehensive data currently available.

Furthermore, the Printed Circuit Board business is subject to a number of risks and uncertainties that relate to raw material price, conditions of customers' market, technological trends, change of foreign exchange, change of tax rules and regulations, disasters, international conflicts and other factors. Meiko therefore wishes to caution that actual results may differ materially from our expectations.